

**DESIGN/PROCESS CHANGE NOTIFICATION**

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

**Implementation of change:**

Expected First Shipment Date for Changed Product : Sep. 11, 2013

Expected First Date Code of Changed Product :1335

**Description of Change (From) :**

The current WLCSP back-end process flow is performed at two Fairchild Semiconductors sites: bumping is done at South Portland wafer fab, USA, the test and tape and reel are performed at the Penang plant, Malaysia.

**Description of Change (To) :**

The WLCSP back-end process flow will be performed at two companies: Fairchild semiconductor and Amkor Technology. Bumping will be done at AMKOR T5 plant in Taiwan, R.O.C. or Fairchild, South Portland. The test and tape and reel will be performed at AMKOR T3 plant in Taiwan, R.O.C. or Fairchild, Penang.

**Reason for Change:**

To further ensure critical supply chain continuity to our customers, Fairchild is expanding the use of an existing and fully qualified source for alternate wafer level chip scale device processing. This change is planned to take effect immediately upon customer approval. Please contact your local Customer Quality Engineer immediately upon receipt of this notification if you require any additional data or samples. Timely approval of this PCN will help to protect your supply chain against any unforeseen supply disruptions

**Affected Product(s):**

FAN48630BUC315X	FAN48630BUC33X	FAN48630UC315X
FAN48630UC33X	FAN48630UC35X	FAN48630UC45X
FAN48630UC50X	FAN48632BUC33X	FAN48632UC33X
FAN48632UC35X	FAN53555BUC08X	FAN53555BUC09X
FAN53555UC00X	FAN53555UC01X	FAN53555UC03X
FAN53555UC042X	FAN53555UC04X	FAN53555UC05X
FAN53555UC08X	FAN53555UC09X	FAN5400UCX
FAN54013BUCX	FAN54013UCX	FAN54015UCX
FAN5401UCX	FAN5402UCX	FAN5403UCX
FAN5404UCX	FAN5405UCX	

Qualification Plan	Device	Package	Process	No. of Lots
Q20120102	FSA2269UCX	UCBBU012	TSMC CM 0.18G	3

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, 4.3V	JESD22-A110	96 hrs	0/135
Static Op Life	150C, 4.3V	JESD22-A108	1000 hrs	0/231
Solderability, Condition C		JESD22-B102	8 hrs	0/33
Temperature Cycle	-40C, 125C	JESD22-A104	1000 Cycles	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20120214	FSA9590UCX	UCBBU030	Maine FS35 5-40S	1
Q20120214	FSA9485UCX	UCBBU025	Maine FS35 5-40S	1

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154
Highly Accelerated Stress Test	110C, 85%RH, 5.4/3.9V	JESD22-A110	264 hrs	0/45
Highly Accelerated Stress Test	110C, 85%RH, 3.5V	JESD22-A110	264 hrs	0/45
Temperature Cycle	-40C, 125C	JESD22-A104	1000 Cycles	0/154